

ABSTRACT OF THE DISCLOSURE

An object of the present invention is to provide a resin composition that is curable at a low temperature of 80°C or lower, preferably at room temperature, and
5 that only contains a small amount of components that volatilize during use (application) or curing and is suitable as a one-part adhesive for use in the manufacture of an image sensor module or an electronic component.

The resin composition of the present invention contains one or more 2-methylene-1,3-dicarbonyl compounds. At least one of the one or more 2-methylene-
10 1,3-dicarbonyl compounds has a molecular weight of 220 to 10,000, and the amount by weight of those of the 2-methylene-1,3-dicarbonyl compounds having a molecular weight of less than 220 relative the entire resin composition of 1 is 0.00 to 0.05. The 2-methylene-1,3-dicarbonyl compounds contain a structural unit represented by formula (I) below.

